

Atty. Docket No. PIA31224/DBE/US  
Serial No: 10/751,198

Amendments to the Claims

1. (Currently Amended) A method for packaging a multi-chip module, comprising the steps of:

connecting a first chip having thereon wafer bumps to lower parts of inner leads of TAB tapes, each of the TAB tapes having thean inner lead and an outer lead, thereby electrical signals being communicated therebetween;

connecting a second chip having thereon wafer bumps to an upper parts of the TAB tapes connected to the first chip, thereby electrical signals being communicated therebetween; and

exccuting an encapsulation step, wherein an underfill material is filled in [a] connecting portions between the TAB tapes and the chips; and

mounting the outer lead of one of the TAB tapes on a patterned circuit.

2. (Currently Amended) The method of claim 1, further comprising the steps of:

connecting a third chip having thereon wafer bumps to an upper part of the second chip;

connecting anthe outer lead of the other TAB tape to one of the wafer bumps of the third chip;

connecting an inner lead of a TAB tape having the inner lead and an outer lead to the other wafer bump of the third chip;

connecting a fourth chip having wafer bumps to the TAB tapes; and

executing an encapsulation step, wherein an underfill material is filled in [a] connecting portions between the TAB tapes and the third and ~~forth~~fourth chips.

3. (Cancelled)

4. (Original) The method of claim 1, further comprising the step of mounting a radiator after a conductive adhesive is coated on an upper part of the second chip.

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5. (Original) The method of claim 1, wherein the chips and the TAB tapes are connected to each other by using gang bonding or single point bonding method.

6. (Original) The method of claim 5, wherein the chips and the TAB tapes are connected to each other by bonding the inner leads of the TAB tapes to the wafer bumps of the chips.

7. (Cancelled)

8. (Original) The method of claim 2, further comprising the step of mounting a radiator after a conductive adhesive is coated on an upper part of the second chip.

9. (Original) The method of claim 2, wherein the chips and the TAB tapes are connected to each other by using gang bonding or single point bonding method.

10. (Original) The method of claim 9, wherein the chips and the TAB tapes are connected to each other by bonding the inner leads of the TAB tapes to the wafer bumps of the chips.

11. (Original) The method of claim 2, further comprising the step of accumulating a plurality of chips having thereon wafer bumps and a plurality of TAB tapes having an inner lead and an outer lead on the fourth chip.